

Title (en)  
Encapsulating composition for use on spliced cable

Title (de)  
Einbettzusammensetzung für gespleisstes Kabel

Title (fr)  
Composition d'encapsulation pour câble épissé

Publication  
**EP 0918338 A1 19990526 (EN)**

Application  
**EP 98309194 A 19981110**

Priority  
US 97413897 A 19971119

Abstract (en)  
An encapsulating material for use on the spliced connections of cable connectors is disclosed. The encapsulating material protects the spliced connections from signal disruptions attributable to both moisture and debris transported onto the cable connectors by insects. The encapsulating material is a mixture of a styrene-rubber block copolymer and a microbe-resistant extender material. Microbe-resistant extender materials that are hydrophobic include branched hydrocarbon compounds and silicon compounds. The encapsulating material optionally includes polyethylene. The polyethylene improves the flow resistance of the encapsulating material.

IPC 1-7  
**H01B 7/28**

IPC 8 full level  
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CPC (source: EP)  
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Citation (search report)  
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• [A] EP 0749128 A2 19961218 - AT & T CORP [US]  
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• [PX] PATENT ABSTRACTS OF JAPAN vol. 098, no. 011 30 September 1998 (1998-09-30)

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